

P50N-UT-A

UV LED

Introduction

The P50N-UT-A LED is a compact, low profile and high performance LED suitable for a wide array of UV applications.

The P50N-UT-A LED is designed to give maximum thermal and optical performance. The P50-UT-A LED is reflow solderable under standard SMT process.



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RoHS Compliant

Features

-  Excellent Operating Life
-  High Efficacy
-  Low Thermal Resistance
-  SMD Device
-  Instant Light
-  Fully Dimmable
-  RoHS Compliant

Characteristics

Absolute Maximum Ratings

Parameter	Rating
	UV
Maximum DC Forward Current (mA)	180 mA
LED Junction Temperature	125°C
LED Operating Temperature	-40°C~110°C
Storage Temperature	-40°C~110°C
Soldering Temperature	Max. 260°C / Max. 10sec. (JEDEC 020c)
Reverse Voltage	Not designed to be driven in reverse bias
Preconditioning	Acc. to JEDEC Level 3

General Characteristics at 150mA (Tj=25°C)

Part number	Color	Peak Wavelength λ_p (nm)		$2\theta_{1/2}$
		Min	Max	
P50N-UT-A	UV	380	420	Lambertian

Part number	Color	Performance at Test Current (150mA)			
		Group	Minimum Radiometric Power (mW)	VF	
				Min	Max
P50N-UT-A	UV	B3	85	2.8	3.8
		C1	100	2.8	3.8
		C2	120	2.8	3.8
		C3	140	2.8	3.8

Remarks:

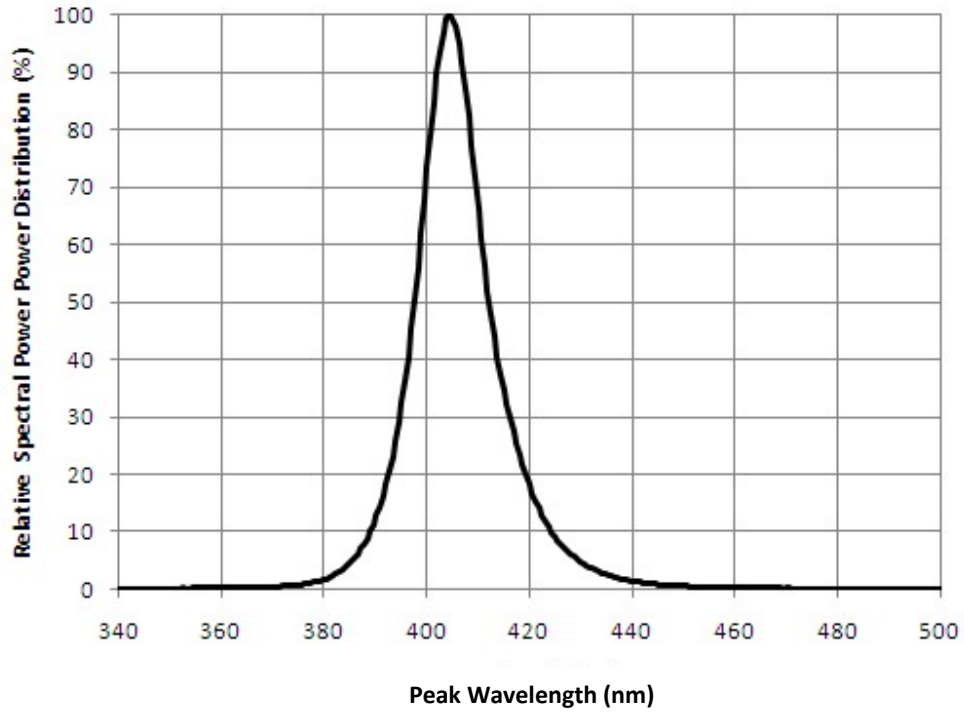
1. Radiometric power is measured with an accuracy of $\pm 10\%$
2. The forward voltage is measured with an accuracy of $\pm 0.1V$

Notes:

1. The peak wavelength is measured with an accuracy of $\pm 1nm$
2. Minimum and maximum value refers to the limits and set up of SemiLEDs' testers. All other measurement data are defined as long-term production mean values and are only given for reference.
3. A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system. Life support devices or systems are intended (i) to be implanted in the human body, or (ii) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered. Components used as a critical component must be approved in writing by SemiLEDs.
4. These devices emit high intensity UV/NUV light. Necessary precautions must be taken during operation. Do not look directly into the light or look through the optical system when in operation. Protective eyewear should be worn at all times during operation.
5. Lens discoloration may occur with prolonged exposure to UV/NUV light. Lens material will need to be tested for UV/NUV light compatibility and durability.

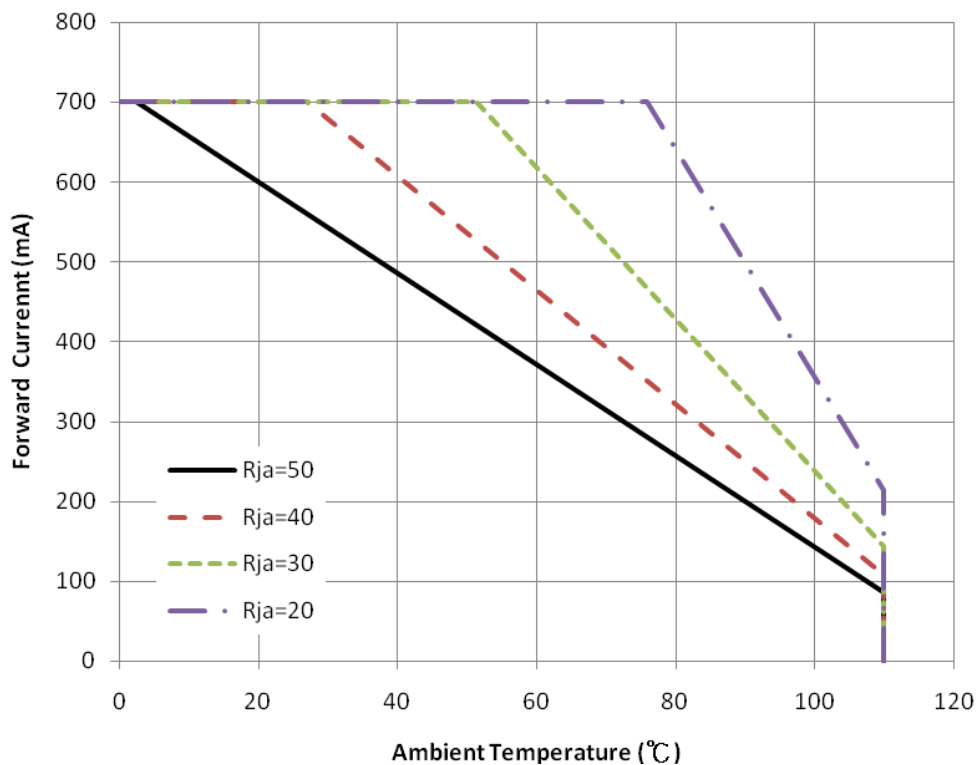
Caution: Users are requested to comply with the laws and public regulations concerning safety.

Relative Spectral Power Distribution, Tc=25 °C



Thermal Design

Thermal design of the end product is important. The thermal resistance between the junction and the solder point ($R_{\theta_{j-l}}$) is $10^{\circ}\text{C}/\text{W}$, and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (R_{ja}) by the following equation.

$$T_j = T_a + R_{ja} * W$$

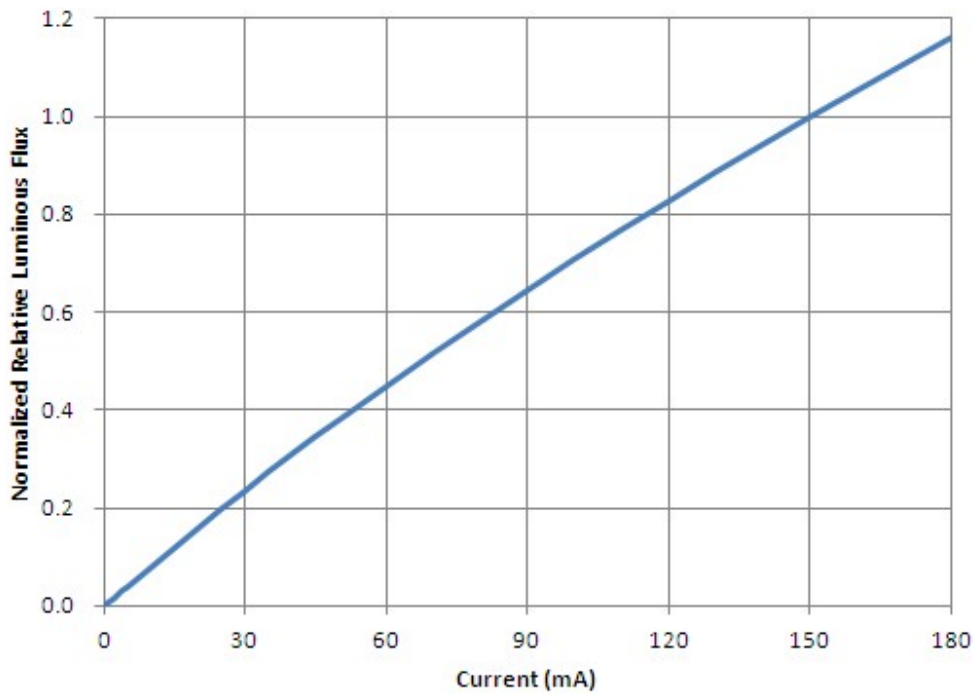
T_j : LED junction temperature

T_a : Ambient temperature

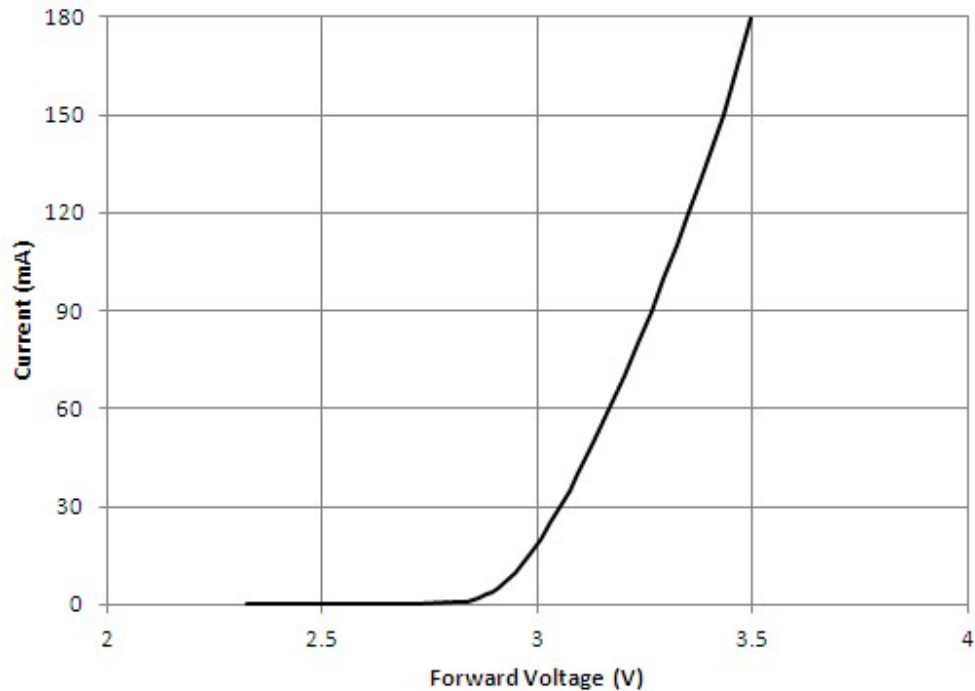
R_{ja} : Thermal resistance between the junction and ambient

W : Input power ($I_F * V_F$)

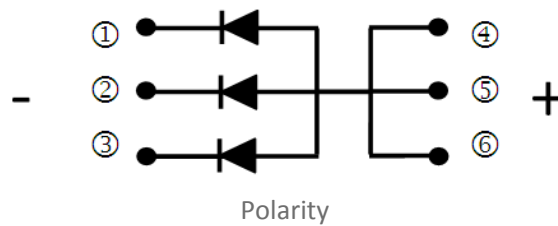
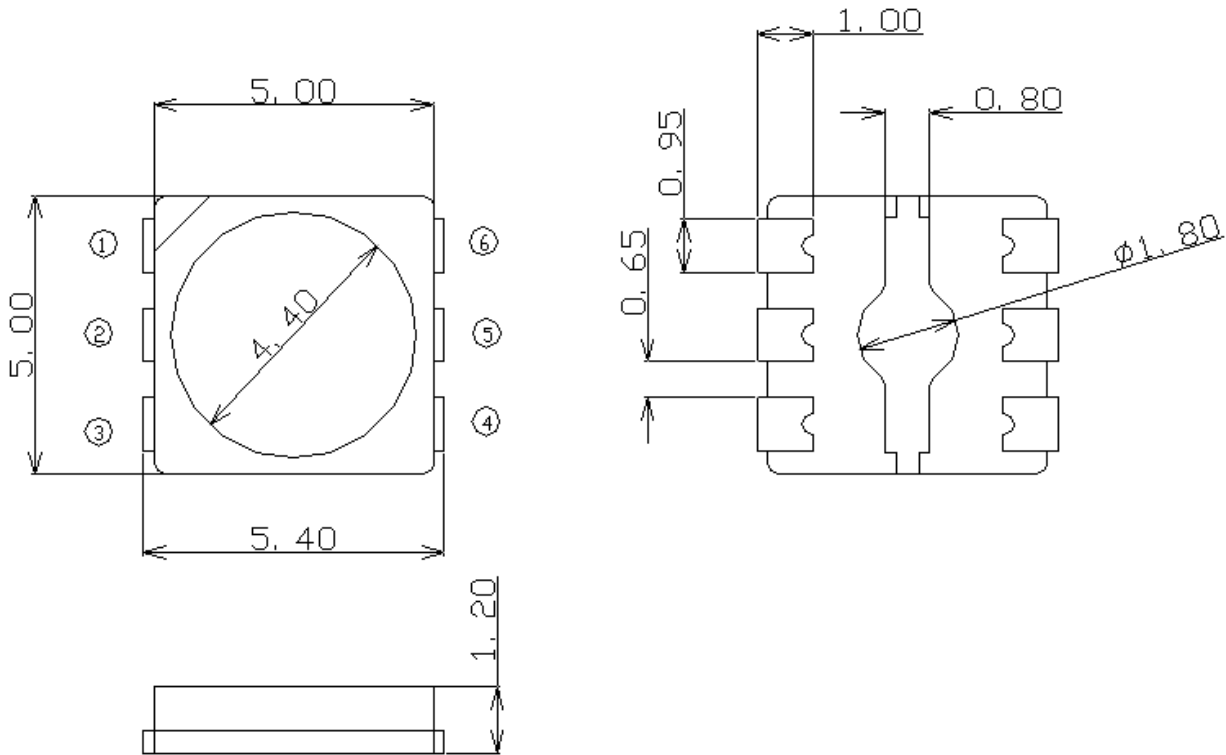
Typical Forward L-I Characteristics (Tj=25°C)



Typical Forward I-V Characteristics (Tj=25°C)



Mechanical Dimensions

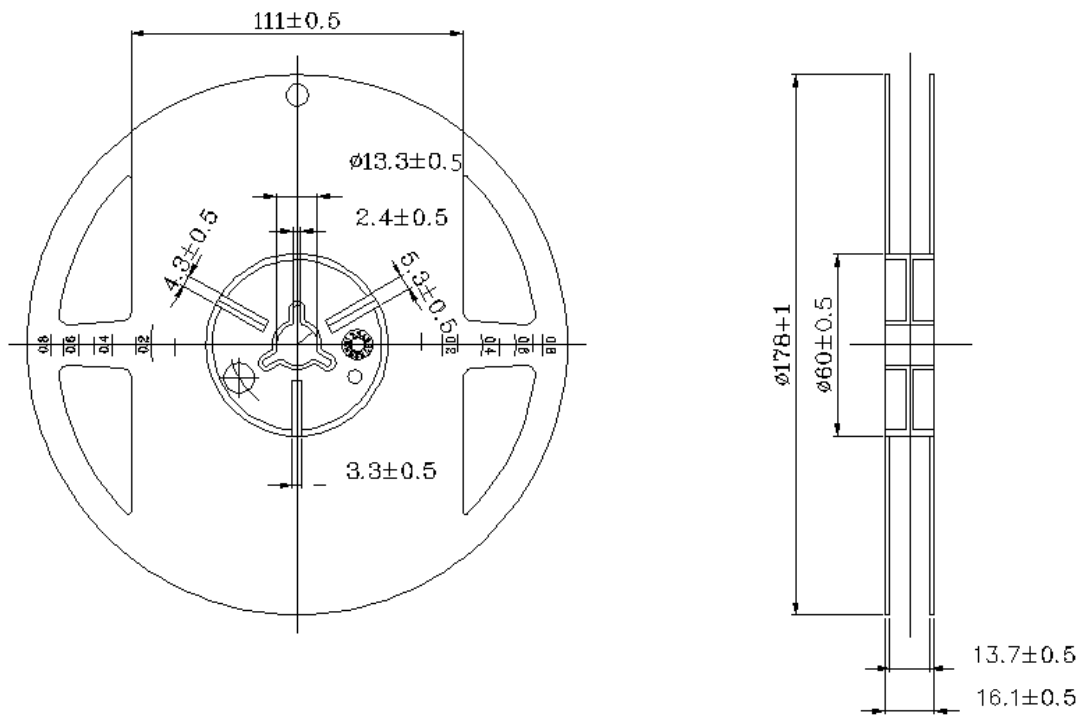


Notes :

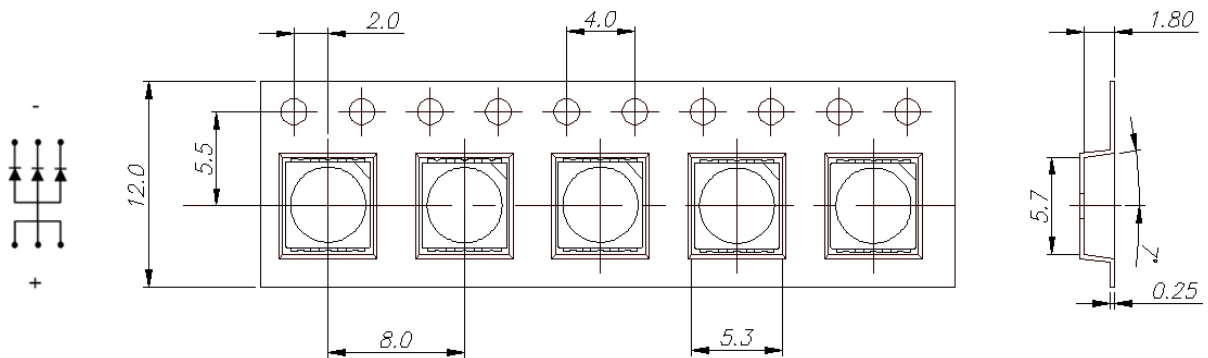
1. Drawings are not to scale.
2. All dimensions are in millimeter.
3. General tolerance is $\pm 0.2\text{mm}$.
4. The polarity of die heat sink at bottom is Anode; please make sure polarity isolation on MCPCB is done correctly.
5. The Cathode is denoted by the bar (minus sign) on plastic body.

Shipping Package Information

Reel Dimension



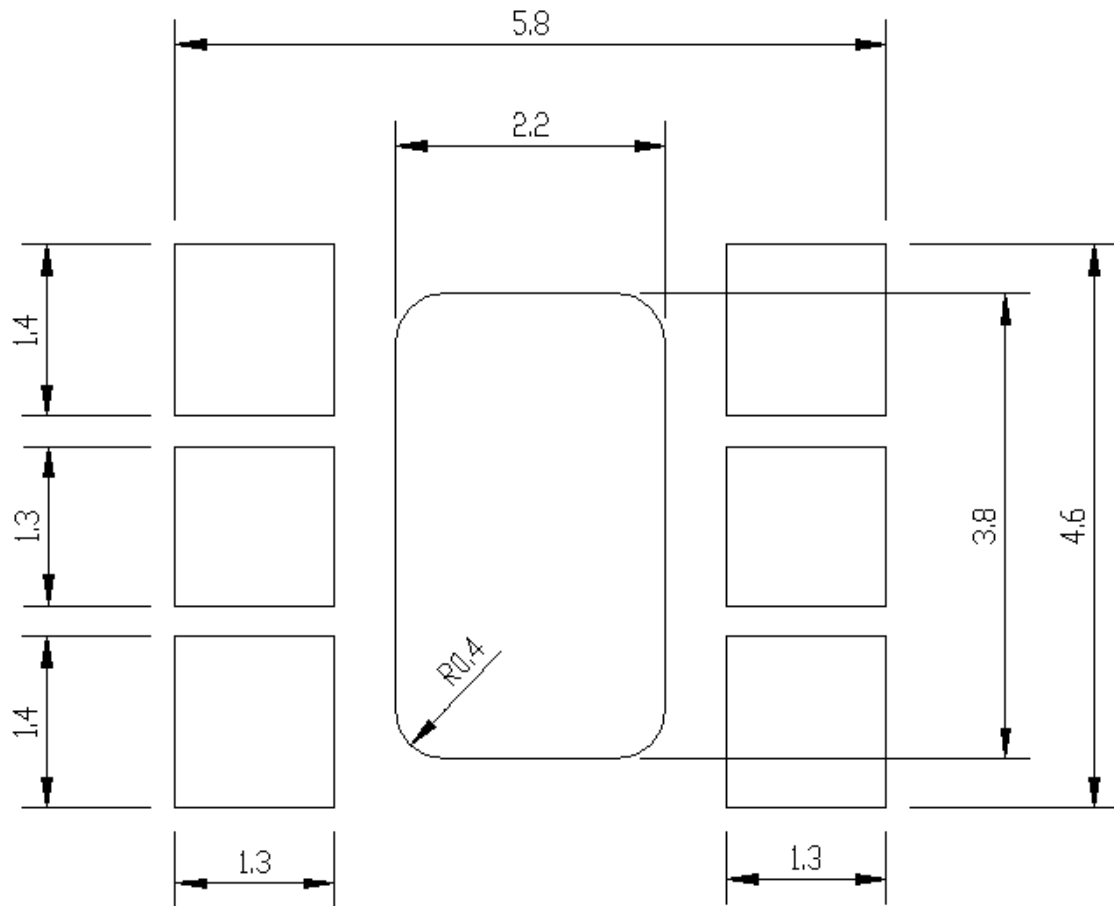
Carrier Tape



Notes :

1. All dimensions are in millimeter
2. Tolerance for fixed dimensions are 0.1mm
3. Packing unit: 1,000pcs/ reel (ϕ 178mm)

Recommended Solder Pad Design

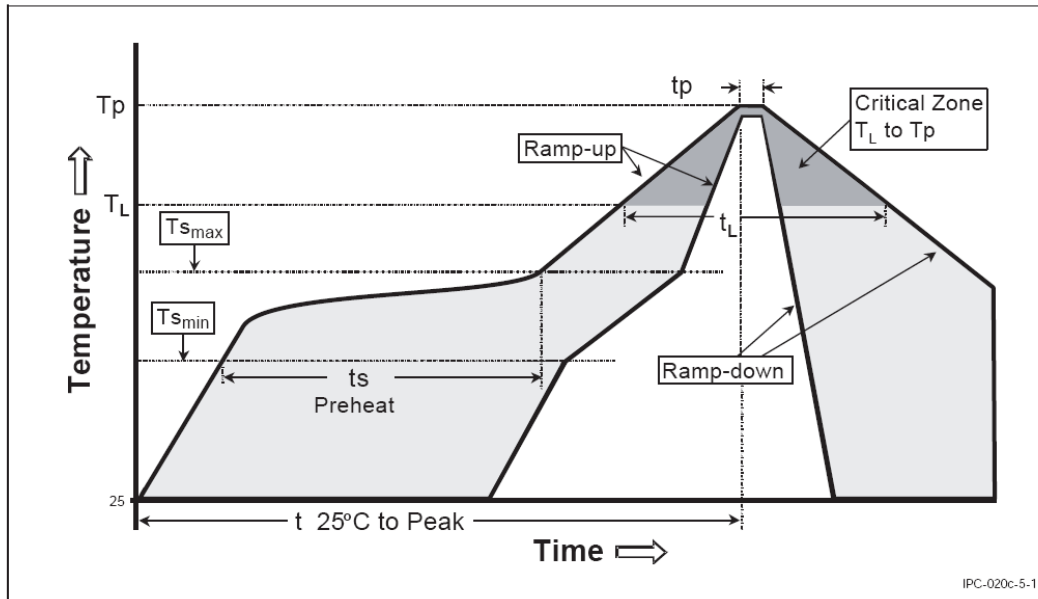


Notes :

1. Drawing is not to scale
2. All dimensions are in millimeter

Recommended Soldering Profile

LEDs can be soldered using the parameter listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is advised for the LEDs.



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-up Rate ($T_{s_{max}}$ to T_p)	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min($T_{s_{min}}$)	100°C	150°C
- Temperature Max($T_{s_{max}}$)	150°C	200°C
- Time($t_{s_{min}}$ to $t_{s_{max}}$)	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature(T_L)	183°C	217°C
- Time(t_L)	60-150 seconds	60-150 seconds
Peak/classification Temperature(T_p)	215°C	260°C
Time within 5°C of actual Peak Temperature(t_p)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

About Us

SemiLEDs Corporation is a US based manufacturer of ultra-high brightness LED chips with state of the art fabrication facilities in Hsinchu Science Park, Taiwan. SemiLEDs specializes in the development and manufacturing of vertical LED chips in blue (white), green, and UV using a patented copper alloy base. This unique design allows for higher performance and longer lumen maintenance. In December 2008, The World Economic Forum recognized SemiLEDs innovations with the 2009 Technology Pioneer Award. SemiLEDs is fully ISO 9001:2008 Certified

SemiLEDs is a publicly traded company on NASDAQ Global Select Market (stock symbol "LEDS"). For investor information, please contact us at investors@semileds.com.

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